

WIRE BOND-LESS ELECTRONIC COMPONENT FOR USE WITH AN EXTERNAL  
CIRCUIT AND METHOD OF MANUFACTURE

ABSTRACT OF THE DISCLOSURE

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A wire bond-less electronic component is for use with a circuit external to the wire bond-less electronic component. The wire bond-less electronic component includes a support substrate (110, 410), an electronic device (130) over the support substrate, and a cover (140, 440, 540) located over the electronic device and the support substrate. The cover includes an interconnect structure (141, 441, 541) electrically coupled to the electronic device and adapted to electrically couple together the electronic device and the circuit for providing impedance transformation of an electrical signal between the electronic device and the circuit.

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